

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Byung-Jun Song	11/09/2006
RECEIVING PARTY DATA	
Name:	Seoul Laser Dieboard System Co., Ltd.
Street Address:	1029-30 Hogac-Dong, Dongan-Ku
City:	Anyang City
State/Country:	REPUBLIC OF KOREA
Name:	Seoul Laser Dieboard System Co., Ltd
Street Address:	13110 Sunstone Pointe
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92130
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12111857
CORRESPONDENCE DATA	
Fax Number:	(619)235-0398
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	619-238-1900
Email:	Docketing@procopio.com
Correspondent Name:	Procopio, Cory, Hargreaves & Savitch LLP
Address Line 1:	530 B Street, Suite 2100
Address Line 4:	San Diego, CALIFORNIA 92101
ATTORNEY DOCKET NUMBER:	113748-2010C2
NAME OF SUBMITTER:	Samuel S. Lee

CH \$40.00 12111857

500528467

PATENT
 REEL: 020885 FRAME: 0009

Total Attachments: 3

source=assignment_2010C2#page1.tif

source=assignment_2010C2#page2.tif

source=assignment_2010C2#page3.tif

PATENT

REEL: 020885 FRAME: 0010

**RECORDATION FORM COVER SHEET
PATENTS ONLY**

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)
Byung-Jun Song

2. Name and address of receiving party(ies)

Name: Seoul Laser Dieboard System Co., Ltd

Internal Address: _____

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) 11/09/2006

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Joint Research Agreement

☐ Government Interest Assignment

☐ Executive Order 9424, Confirmatory License

☐ Other _____

Street Address: 1029-30 Hogac-Dong, Dongan-Ku

City: Anyang City

State: Kyunggido

Country: Republic of Korea Zip: _____

Additional name(s) & address(es) attached? ☒ Yes ☐ No

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)
12/111,857

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☐ NO

5. Name and address to whom correspondence concerning document should be mailed:

Name: Samuel S. Lee

Internal Address: _____

Street Address: 530 B. Street, Suite 2100

City: San Diego

State: CA Zip: 92101

Phone Number: 619-238-1900

Fax Number: 619-235-0398

Email Address: ssl@procopio.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

☐ Authorized to be charged by credit card

☒ Authorized to be charged to deposit account

☐ Enclosed

☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____

Expiration Date _____

b. Deposit Account Number 50-2075

Authorized User Name Samuel S. Lee

9. Signature: _____

Signature

April 29, 2008

Date

Samuel S. Lee

Name of Person Signing

Total number of pages including cover sheet, attachments, and document:

3

Additional Receiving Party

Seoul Laser Dieboard System Co., Ltd.
13110 Sunstone Pointe
San Diego, CA 92130

Application No.: to be assigned
Filing Date: 11/09/2006

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in FOLDING SYSTEM FOR A CUTTING BLADE (Application Number: 11/558,316, Filing Date: 11/09/2006 for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address. (The undersigned hereby authorizes and requests the attorneys of Procopio, Cory, Hargreaves & Savitch LLP, Customer No. 27189 to insert in the appropriate blanks, the serial number and filing date of the application when known.)

AND WHEREAS, SEOUL LASER DIEBOARD SYSTEM CO., LTD, a corporation, with offices at 1029-30 Hogae-Dong, Dongan-Ku Anyang City, Kyunggi-do, Republic of Korea and SEOUL LASER DIEBOARD SYSTEM CO., LTD, a corporation, with offices at 13110 Sunstone Pointe, San Diego, CA 92131 (hereinafter referred to as ASSIGNEES) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries:

NOW THEREFORE for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or their designee(s), as ASSIGNEES or their successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at their own expense;

And I further agree that ASSIGNEES will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment executed on the dates indicated below,

Byung-Jun Song
Name of first inventor

11/09/2006
Execution date of U.S. Patent Application

Residence of first inventor


Signature of first inventor

11/09/2006
Date of Assignment